

Atty. Docket No. CPAC 1017-5  
Appl. No. 10/632,552

PATENT

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CENTRAL FAX CENTER

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos Karnezos )  
Application No.: 10/632,552 )  
Filed: August 2, 2003 )  
Title: Semiconductor multi-package module having )  
package stacked over die-up flip chip )  
ball grid array package and having wire )  
bond interconnect between stacked packages )

Examiner: Chris C. Chu

Group Art Unit: 2815

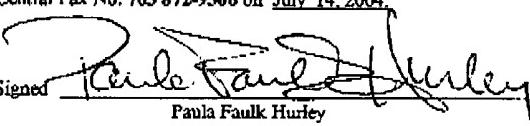
Date: July 14, 2004

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## CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being facsimile transmitted to the  
United States Patent and Trademark Office, at the  
Central Fax No. 703 872-9306 on July 14, 2004.

Signed   
Paula Faulk Hurley

## RESPONSE TO RESTRICTION REQUIREMENT

Dear Sir:

Responsive to the Office action mailed June 30, 2004 (Restriction only), Applicants elect:  
Group I, claims 1-19, 35 and 36.

**Amendments to the Specification** begin on page 2 of this paper.

**A Listing of Claims** is included for the Examiner's convenience, beginning on page 3 of  
this paper.

**Remarks** begin on page 8 of this paper.